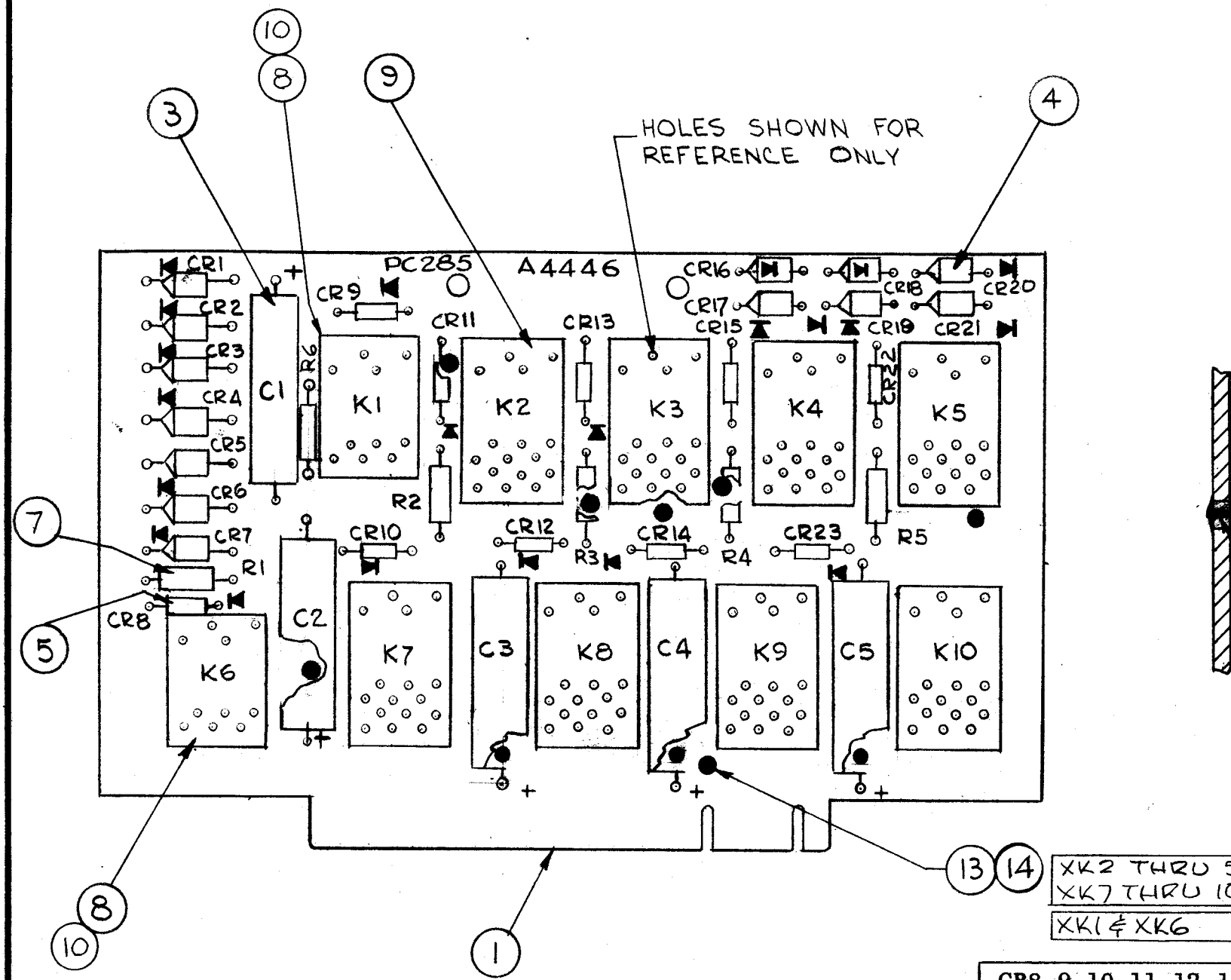


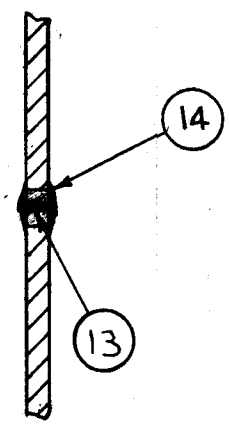
A4446 B

REVISIONS

SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD	APPD
X	EXPERIMENTAL RELEASE	9.16.66	X	RME		
Ø	ORIGINAL RELEASE FOR PRODUCTION	9.21.66	Ø	CV		
A	DELE IT 2 & 6. ADDED 2 IT 7'S & 4 IT 3'S. IT 7 WAS RC20GF320J. ADD NOTE -4	1.25.67	17661	RME		
B	SYM. IT 8 & 9 ADDED; NOTE 2 REVISED	2.13.67	17820	WFO		



HOLES SHOWN FOR REFERENCE ONLY



- 13 14 XK2 THRU 5
XK7 THRU 10
XK1 & XK6
- CR8, 9, 10, 11, 12, 13,
14, 15, 22, 23
- CR1, 2, 3, 4, 5, 6, 7,
16, 17, 18, 19, 20, 21

~ ASSEMBLY NOTES ~

- 1- TO MOUNT COMPONENTS, INSERT LEAD THROUGH PLATED THRU-HOLES.
- 2- USE CAUTION WHEN APPLYING HEAT & SOLDER TO LEAD & FOIL.
- 3- CLEAN & INSPECT AS PER S-676
- 4- FUNGUS PROOFING AS PER TMC SPEC S113.

NOTES

1	LRCA-1	
QTY./UNIT	MODEL USED ON	ASSY. NO.
SCALE	CODE	
1:1		

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REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
X	14	BS100	SOLDER, TIN ALLOY	
X	13	WI100-6	WIRE, ELECTRICAL BUSS	
4	12	RL156-8	RELAY	K7, 8, 9, 10
4	11	RL156-18	RELAY	K2, 3, 4, 5
2	10	RL156-1	RELAY	K1 & K6
8	9	TS171-4	SOCKET, RELAY	
2	8	TS171-5	SOCKET, RELAY	
6	7	RC32GF391J	RES, FXD, COMP	R1, 2, 3, 4, 5, 6
	6	DELETED		
10	5	1N270	SEMICONDUCTOR, DEVICE, DIODE	
13	4	1N2484	SEMICONDUCTOR, DEV, PC, DIODE	
15	3	CE105-50-50	CAPACITOR, FXD, ELECT	C1, 2, 3, 4, 5
	2	DELETED		
1	1	PC285	PRINTED CIRCUIT BOARD	

EATON

LIST OF MATERIAL

MATERIAL		THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK			
FINISH		TITLE ASSY. PRINTED CIRCUIT BOARD			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES		DRAWN G.D.L.	DATE 9-6-66	FINAL APPROVAL <i>J.E. Eaton</i>	
		CHECKED <i>[Signature]</i>	DATE	DATE 9/22/66	
DECIMALS .X ± .05 .XX ± .01 .XXX ± .005		FRACTIONS ± 1/64 ANGLES ± 0° 30'		TOLERANCES	
		ELECT. DES. <i>[Signature]</i>	DATE 9/22/66	A4446	
		MECH. DES.	DATE	B	
		SHEET		REV. LTR.	